

ABSTRACT OF THE DISCLOSURE

A radiator structure has a circuit board, at least one conductive plate, a radiator board and at least two lock attachments, and reduces the entire radiator structure size to permit micro miniaturization designs and increase

5 the space efficiency without affecting cooling efficiency. The radiator board has a deforming section, which undergoes resilience deformation facing the circuit board to absorb a contact pressure generated between the radiator board, the conductive plate and the microprocessor chip. Use of a spring to absorb the contact pressure is thus not required, which decreases the

10 number of parts and manufacturing costs.